

Evaluation of 157nm Substrate Damage During Mask Repair

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Outline:

- Introduction - Key challenges in mask repair
- Evaluation of 157nm substrate damage during repair
 - Experimental set up
 - Results
- Comparison with other low damage repair alternatives
- Summary

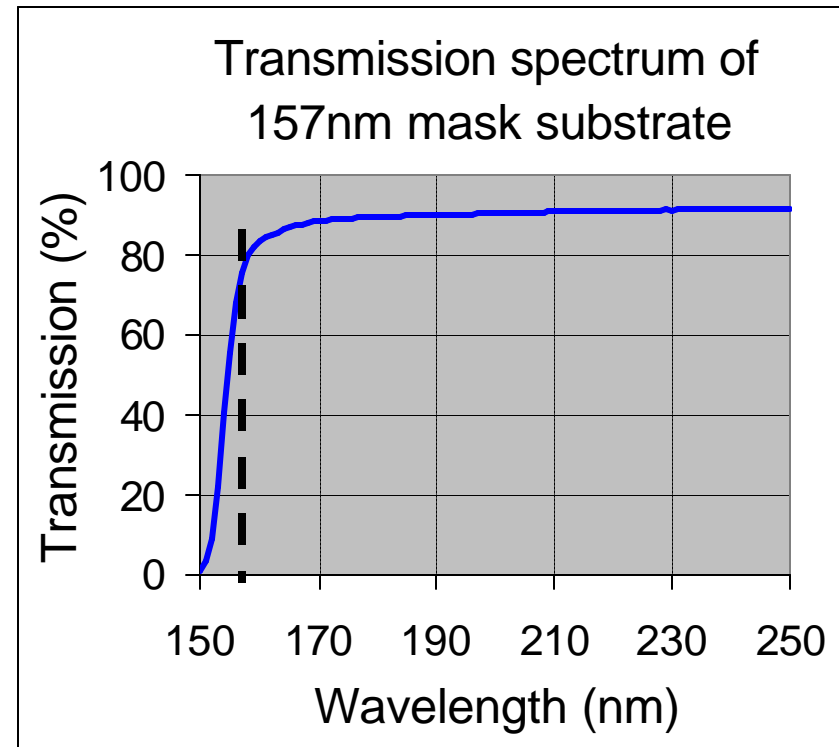
Key issues in FIB mask repair

- Focused Ga ion beam (FIB) based repair is approaching its fundamental limits
 - Even the low Ga ion dose used in defect search and imaging can cause unacceptable transmission loss (Ga stain).
 - Difficult to manage 'river-bed' and 'over-scan' effect in tight features
- Surface charging hinders edge placement precision

Specific issues in 157nm mask repair

■ Fused silica substrate:

- 157nm near absorption edge
- Expected high sensitivity to Ga stain and organic contamination in repair



■ Ga stain:

- Ga ion projected range is about 40-60nm under repair conditions
- Removing this layer would create a 60-90° phase defect

Evaluation of substrate damage during repair

■ Motivation:

- How will Ga ion FIB repair affect 157nm transmission?

■ Metrology limits:

- Resist is not yet adequate for defect printability studies
- No AIMS tool available for transmission measurement

■ Instead, we perform direct measurements of substrate damage:

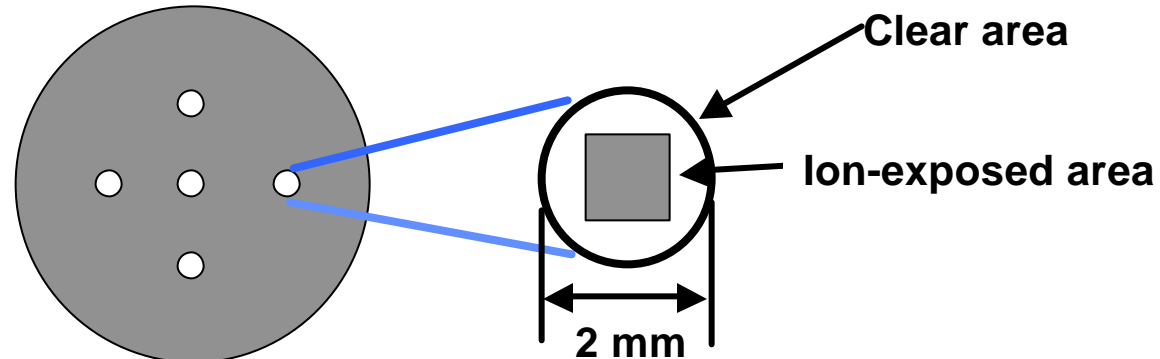
- Assess Ga stain impact on 157nm transmission
- Evaluate other alternative sources: Kr-ion, e-beam

Intel/FEI/MIT-LL experiments

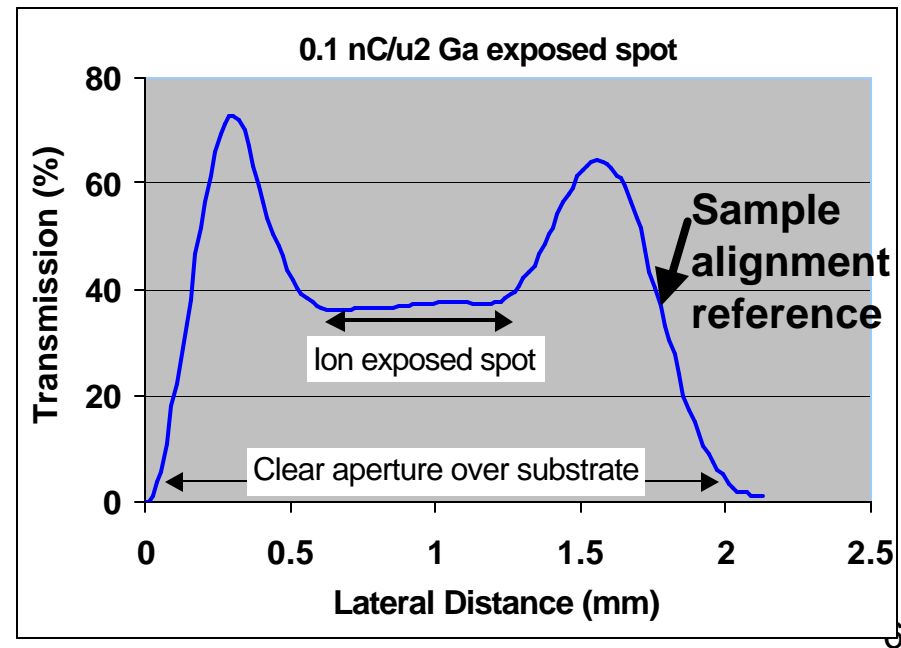
- Substrate material: ¼" thick, 1" dia. disk (T~75% @157nm)
- Exposure conditions on 1mm x1mm area:
 - 30kV Ga ions, 30kV Kr ions and 1kV electron beam
 - Two exposure doses:
 - Low dose ($0.01\text{nC}/\mu^2$) – Received by substrate during defect search and imaging
 - High dose ($0.1\text{nC}/\mu^2$) – Partial dose received by substrate during repair
- Post-exposure treatment and measurement:
 - 172nm photon + O₂ clean and transmission measurement on VUV-visible spectrometer @ MIT-LL
 - Surface roughness measurement
 - Wet acid post-clean

Pinhole transmission measurement

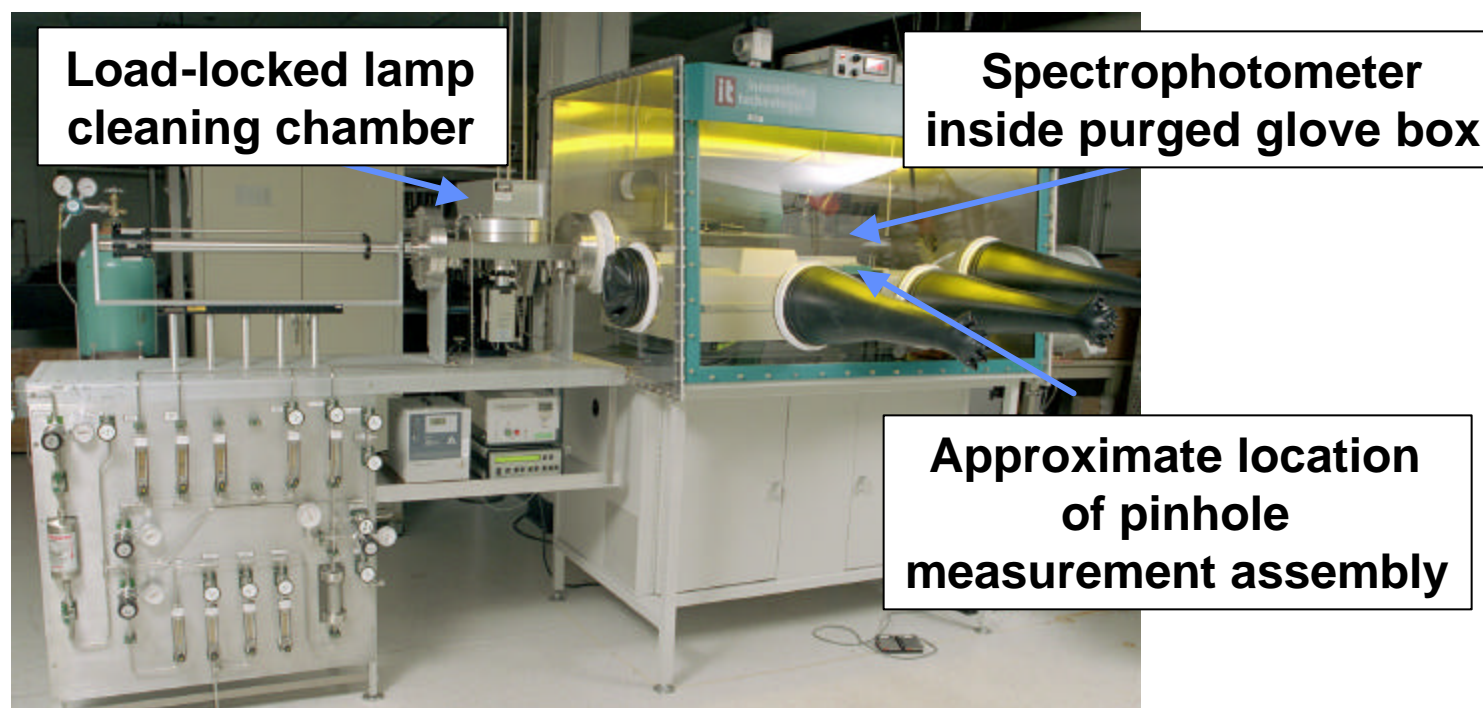
- Overlay template for locating exposed area on substrate



- Apertured spectrometer:
 - 250 μm spatial resolution
 - 0.2% repeatability error



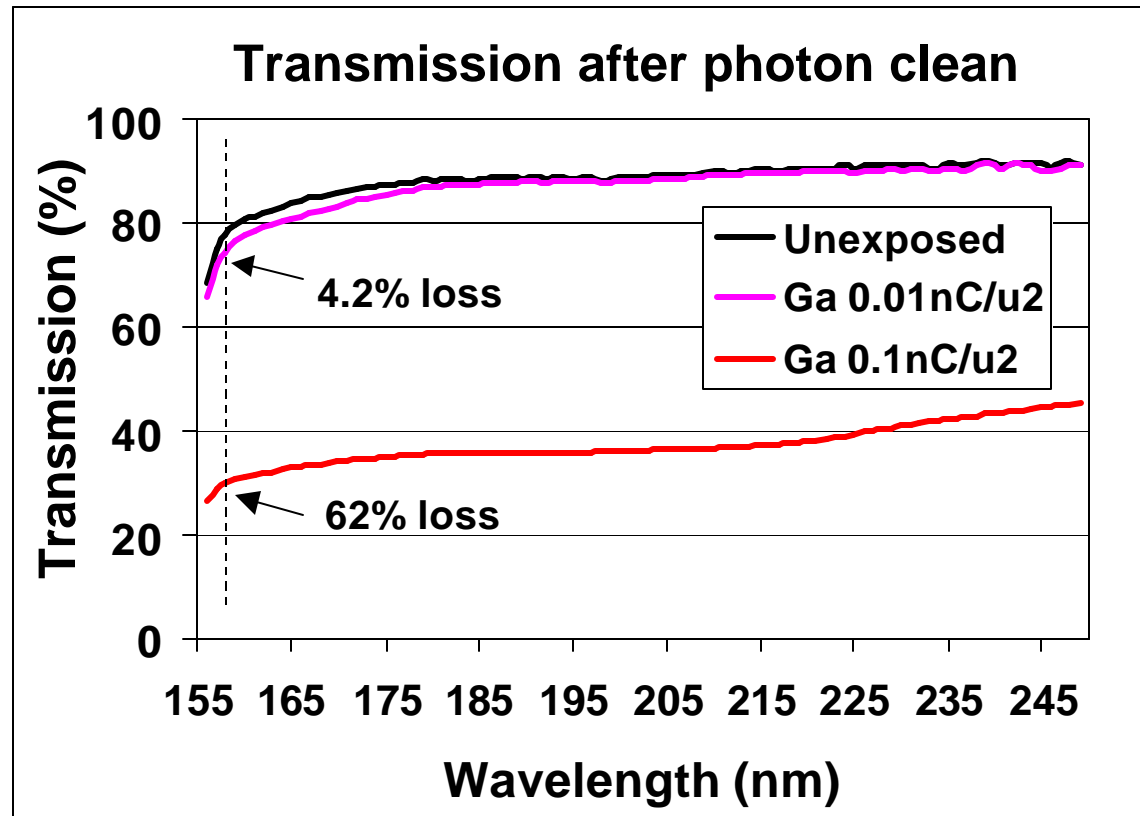
Spectrometer system



■ In the sample compartment:

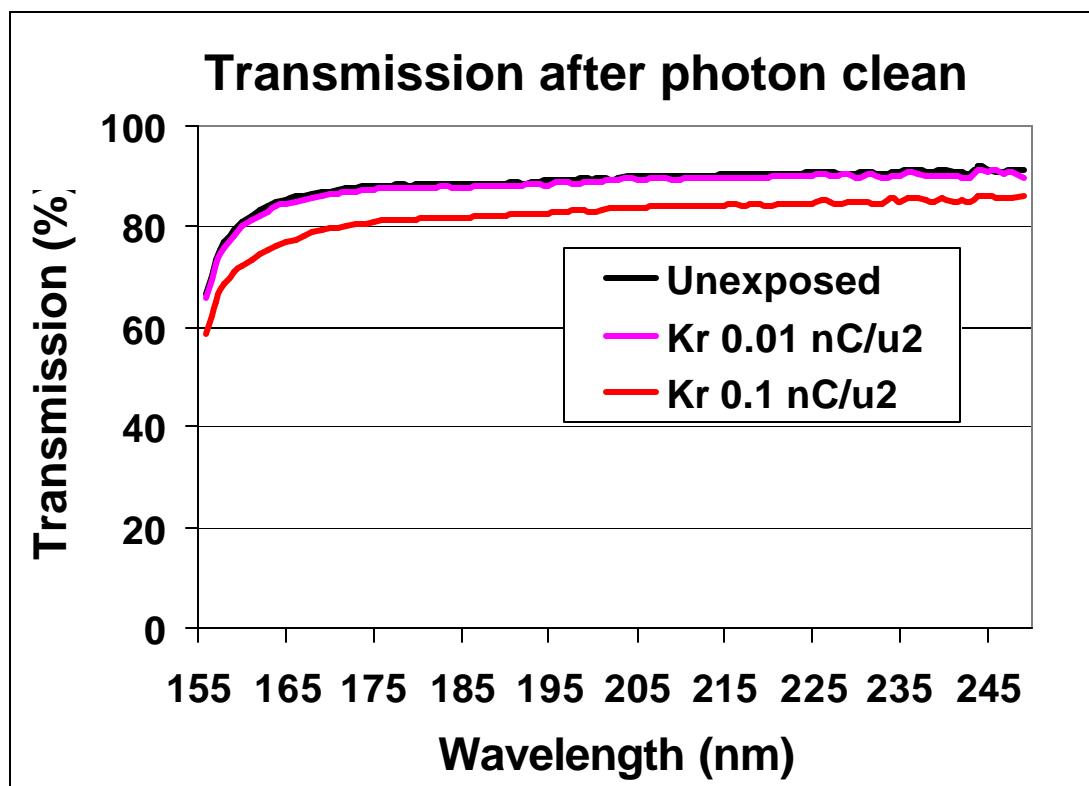
- $[O_2] < 0.25$ ppm
- $[H_2O] < 0.5$ ppm
- $THC < 2$ ppb

Ga ion stain results @157nm



- 4.2% transmission loss @ 157nm during defect imaging
- 62% transmission loss @157nm after 0.1nC/ μ^2 repair

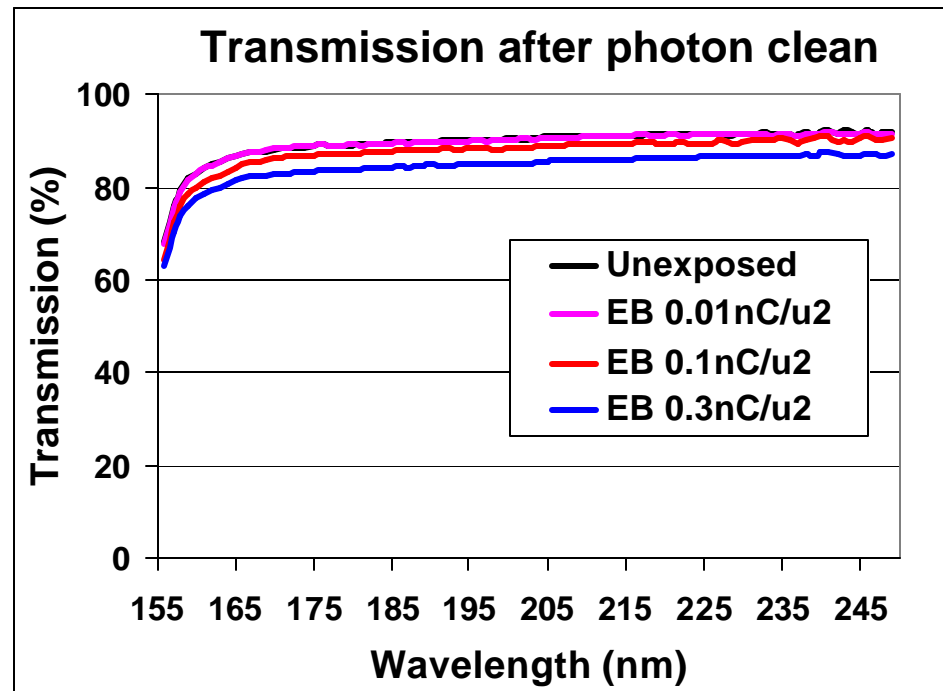
Kr ion stain results @157nm



- 1.2% transmission loss @157nm during defect imaging
- 11% transmission loss @157nm after 0.1nC/ μ^2 repair

E-beam stain results

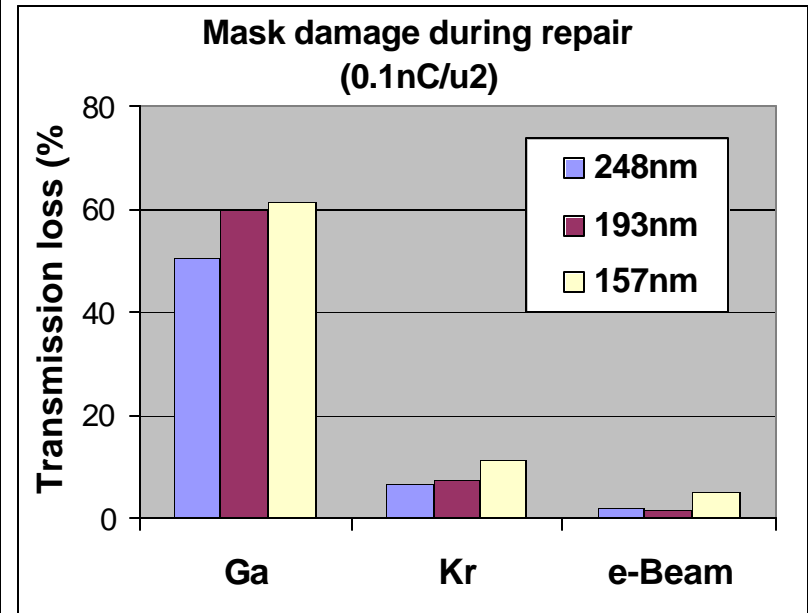
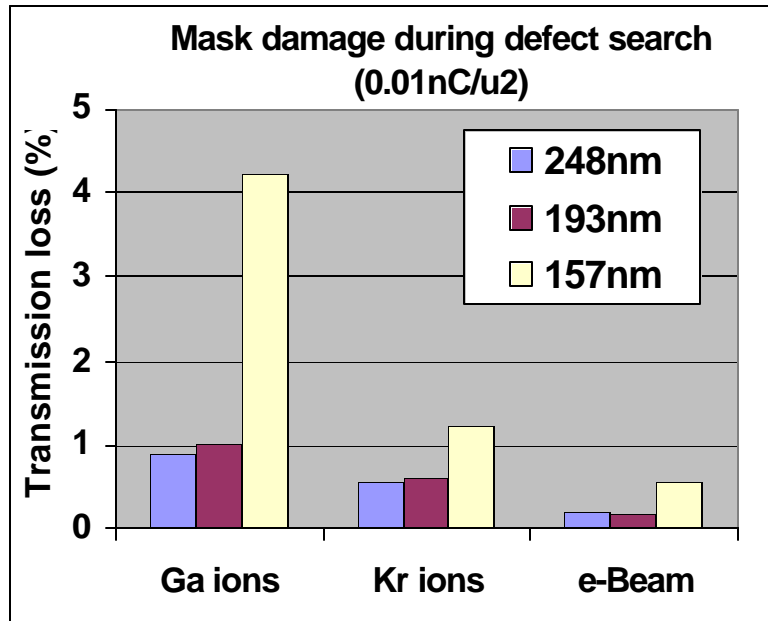
- Advantages of e-beam based repair over the use of ions:
 - Damage-free and pure chemical process – high etch selectivity
 - High spatial resolution



- 0.6% transmission loss @157nm during defect imaging
- 5% transmission loss @157nm after 0.1nC/ μ^2 repair₁₀

Comparison summary

- In general, transmission loss is more at 157nm



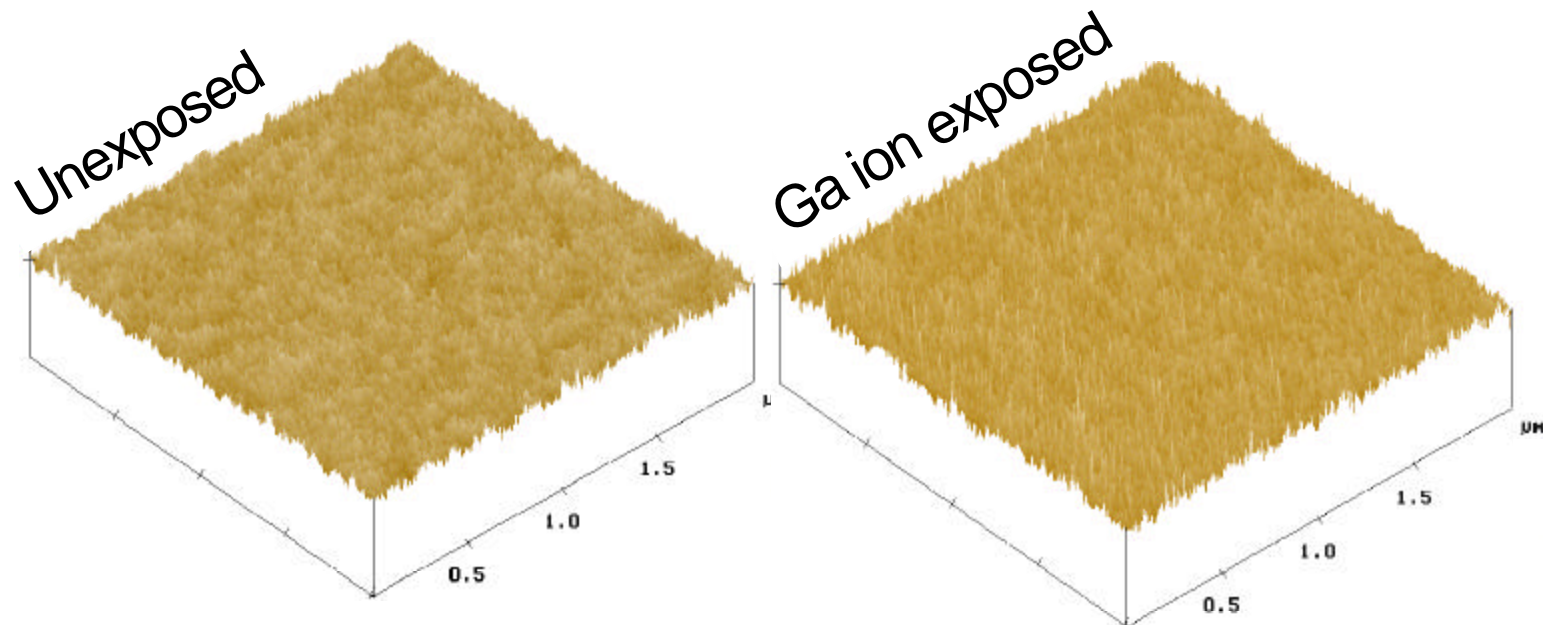
- Possible causes:

- Ga ion stain
- Surface damage (increased roughness)
- Remaining organic contamination after 172nm photon+O2 clean (important at low dose)

Surface roughness

- Exposure did not change surface roughness

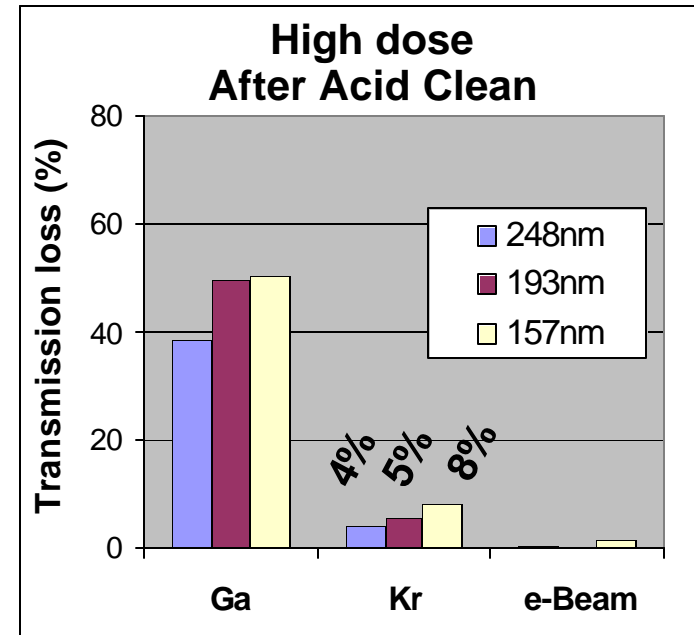
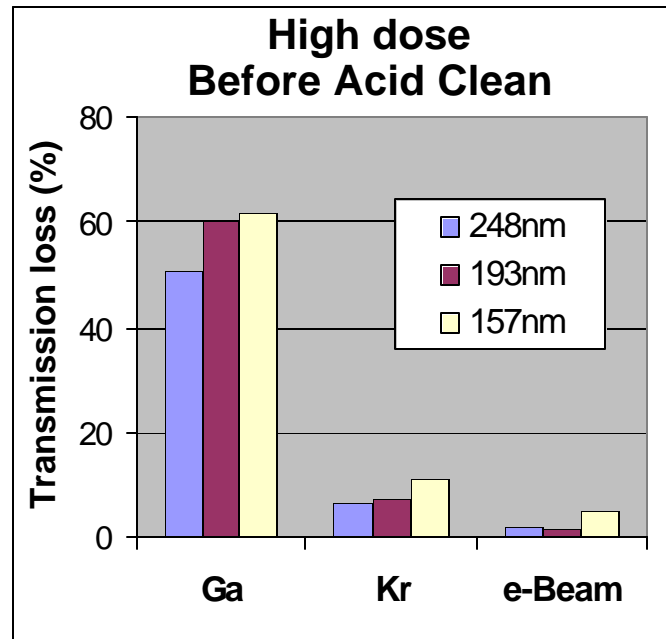
	<u>Un-exposed</u>	<u>Ga ion</u>	<u>Kr ion</u>	<u>e-beam</u>
Range (nm):	2.3	3.3	2.4	2.8
RMS (nm):	0.23	0.28	0.25	0.23



- Surface roughness does not cause transmission loss

Transmission after acid wet clean

- Used $\text{H}_2\text{SO}_4 + \text{H}_2\text{O}_2$ acid to clean the exposed substrates



- Transmission loss partially recovered after acid clean:
 - High dose: ~10% transmission recovery
 - Low dose: < 0.5% transmission loss after clean
- Effect is believed to be from organic removal.

Summary

- We evaluated the transmission loss of 157nm mask substrate after exposure to Ga ions, Kr ions and electron beams as measured by spectrophotometer with 250nm spatial resolution.
- Ga ions caused ~10X more transmission loss for the mask substrate compared to Kr ions and e-beam.
- Partial transmission can be recovered by wet acid clean, possibly from the removal of organic contamination remained after photon clean
- Alternative damage-free mask repair using Kr ions or electrons cause minimal damage to the mask substrate.

Acknowledgements: Ron Wu, Tim Pinkerton

Backup foil: Spectrometer layout

■ Top view of spectrometer layout

